

# **3D IC Integration And Packaging**

**By John Lau**

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3D IC packaging and 3D IC integration are different. In general, the TSV Dr. John H. Lau has been the Senior Technical Advisor of ASM since July 2015.

<http://www.iwllpc.com/tutorials.cfm>

In microelectronics, a three dimensional integrated circuit (3D IC) It is unclear who should own the 3D IC integration and packaging/assembly.

[http://en.wikipedia.org/wiki/Three-dimensional\\_integrated\\_circuit](http://en.wikipedia.org/wiki/Three-dimensional_integrated_circuit)

Through-Silicon Vias for 3D Integration provides cutting-edge information on TS Through-Silicon Vias for 3D Integration John Lau 3D IC integration with

<https://www.overdrive.com/media/1052926/through-silicon-vias-for-3d-integration>

John Lau is the author of Basics Fashion Design 09 (4.00 avg rating, 2 ratings, 0 reviews, published 2011), Reliability of RoHS-Compliant 2D and 3D IC In

[http://www.goodreads.com/author/show/1703457.John\\_Lau](http://www.goodreads.com/author/show/1703457.John_Lau)

and integrated circuits (IC) integration packages.Design/methodology/approach 3D LED and IC wafer level packaging. John Lau (Industrial

<http://www.emeraldinsight.com/doi/abs/10.1108/13565361011034786>

John Lau Through-Silicon Vias for 3D Integration integrated circuit. through-silicon vias for 3d integration,

<http://yhcdpdf.ijoy365.com/through-silicon-vias-for-3d-integration-john-lau-60267126.pdf>

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Embedded Technology Forum Presentation Download 3D integration consists of 3D IC packaging, Dr. John Lau, Fellow, Electronics

<http://www.semi.org/en/node/42906>

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<http://www.bokus.com/bok/9780071848060/3d-ic-integration-and-packaging/>

Reading time (words) 3D IC integration is taking the semiconductor industry by storm. It has been: (a) impacting chip suppliers, fab-less design houses, foundries

<http://flex.icconnect007.media/index.php/article/87298/3d-ic-integration-and-3d-ic-packaging/87301/>

A comprehensive guide to 3D IC integration and packaging methods and solutions, featuring detailed e

<http://www.tlsnz.co.nz/3d-ic-integration-and-packaging-9780071848060>

Vias for 3D Integration (9780071785150) av John Lau 3D IC integration with interposers Thermal management of 3D IC integration 3D IC packaging

<http://www.bokus.com/bok/9780071785150/through-silicon-vias-for-3d-integration/>

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<http://www.barnesandnoble.com/c/john-lau>

(LED) and integrated circuits (IC) integration packages. 3D LED and IC wafer level packaging John Lau, Ricky Lee, Matthew Yuen and Philip Chan

<http://www.emeraldinsight.com/doi/pdfplus/10.1108/13565361011034786>

3D Architectures for Semiconductor Integration and Packaging 3D ASIP provides excellent exposure for sponsors and exhibitors.

<http://3dasip.org/>

Following the course of 3D IC integration and 3D Packaging. Posted by Francoise von Trapp at 12 on the developing area of 3D IC Packaging during my tenure as

<http://francoisevontrapp.blogspot.com/>

TSV Interposers With Embedded Microchannels for 3D IC and LED Integration. John Lau, Heng -Chieh Chien, Ray and Exhibition on Packaging and Integration of

<http://proceedings.asmedigitalcollection.asme.org/proceeding.aspx?articleid=1630178>

PD30, Thursday, March 27, 2014, from 2:00 to 5:00 pm. 2.5D/3D IC integration is taking the semiconductor industry by storm. It has been: (a) impacting chip suppliers

<http://blog.ipc.org/2014/03/07/3d-ic-packaging-and-2-5d3d-ic-integration/>

Reliability of RoHS-Compliant 2D and 3D IC John Lau. Abstract: Unique free interconnect reliability of 3D packaging and 3D IC integration Provides information

<http://www.worldcat.org/title/reliability-of-rohs-compliant-2d-and-3d-ic-interconnects/oclc/659763935>

ECTC 2013: 2.5D and 3D IC Technology Preview. and 3D Si Integration, lead by John Lau, (3D Reliability and Packaging Challenges)

<http://www.3dincites.com/2013/05/ectc-2013-2-5d-and-3d-ic-technology-preview/>

Through-Silicon Vias for 3D Integration eBook: John Lau: Amazon.co.uk: Kindle Store  
Thermal management of 3D IC integration; 3D IC packaging; Show More

<http://www.amazon.co.uk/Through-Silicon-Vias-Integration-John-Lau-ebook/dp/B008SOCEMW>

The Path to Future Interconnects. August 6, 2015 at 1:00 p.m. ET. Jon Candelaria, Semiconductor Research Corp. s director of interconnect and packaging sciences

<http://electroiq.com/3d-integration/>

Engineering & Transportation Engineering Electrical & Electronics Electronics Optoelectronics (Author John Lau)

<http://www.medical-books.medindia.com/1-13723-John+Lau-Author-sr-1>

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ECTC 2014: A Preview of 2.5D and 3D Activities. , 3D IC Packaging and 3D Si Integration, Lau will discuss supply chains and the critical process and

<http://www.3dincites.com.php53-6.ord1-1.websitetestlink.com/2014/05/ectc-2014-preview-2-5d-3d-activities/>

3D IC integration will be a hot topic at IPC APEX EXPO

<http://blog.ipc.org/2015/01/21/3d-ic-integration-and-3d-ic-packaging-2/>

ECTC 2015: Advanced Packaging Sets This was good sign after it appeared there was a lull in 3D integration progress for the past According to John Lau,

<http://www.3dincites.com/2015/05/ectc-2015-advanced-packaging-sets-sail-in-san-diego/>

Public Information. Overview and Outlook of 3D IC Packaging, 3D IC Integration, and 3D Si Integration, John Lau

[https://community.asme.org/eppd\\_journal\\_electronic\\_packaging/w/wiki/10673.public-information.aspx](https://community.asme.org/eppd_journal_electronic_packaging/w/wiki/10673.public-information.aspx)

3D-IC: Ushering in a New Era in the Semiconductor Industry25 Executives Share Technology Insights at the SiP Global Summit. 3-D integration and packaging

<http://www.semi.org/en/node/39566>

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